

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S31	966	(702/182).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/22 12:11
S32	219	S31 and (semiconductor wafer (integrated adj circuit))	US-PGPUB; USPAT	OR	ON	2005/07/22 11:22
S33	173	(702/182).CCLS.	EPO; JPO	OR	OFF	2005/07/22 12:10
S34	6	S33 and (semiconductor wafer (integrated adj circuit))	EPO; JPO	OR	ON	2005/07/22 13:14
S35	189	702/183.ccls. and (semiconductor wafer (integrated adj circuit))	US-PGPUB; USPAT	OR	ON	2005/07/22 11:22
S36	0	702/183.ccls. and (semiconductor wafer (integrated adj circuit))	EPO; JPO	OR	ON	2005/07/22 12:10
S37	0	(702/183).CCLS.	EPO; JPO	OR	OFF	2005/07/22 12:39
S42	417	(324/500).CCLS.	EPO; JPO	OR	OFF	2005/07/22 14:29
S43	261	(324/500).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/22 13:13
S44	1066	(324/537).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/22 14:30
S45	553	S44 and (semiconductor wafer (integrated adj circuit))	US-PGPUB; USPAT	OR	ON	2005/07/22 14:28
S46	414	(324/537).CCLS.	EPO; JPO	OR	OFF	2005/07/22 14:28
S47	54	S46 and (semiconductor wafer (integrated adj circuit))	EPO; JPO	OR	ON	2005/07/22 14:30
S48	0	(324/500).CCLS.	DERWENT ; IBM_TDB	OR	OFF	2005/07/22 14:30
S49	2911	(324/765).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/22 14:30
S50	4261	(324/765).CCLS.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/22 14:30
S51	3955	S50 and (semiconductor wafer (integrated adj circuit))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/07/22 14:30
S52	198	S50 and (semiconductor wafer (integrated adj circuit)) and map	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/07/22 14:31
S53	1686	(257/E21.521).CCLS.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/22 14:58
S54	39	(257/E21.521).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/22 15:00
S55	1647	(257/E21.521).CCLS.	EPO; JPO	OR	OFF	2005/07/22 14:58
S56	1187	(257/E21.525).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/22 15:00
S57	131	(257/E21.525).CCLS.	EPO; JPO	OR	OFF	2005/07/22 15:00
S58	1870	(438/14).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/22 17:23
S59	2	(438/14).CCLS.	EPO; JPO	OR	OFF	2005/07/22 15:01
S60	206	S58 and map	US-PGPUB; USPAT	OR	ON	2005/07/22 15:02
S61	2	(438/14).CCLS.	EPO; JPO	OR	OFF	2005/07/22 17:22
S62	864	(438/16).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/25 11:54
S63	944	(438/17).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/25 12:06
S64	167	(438/16).CCLS.	EPO; JPO	OR	OFF	2005/07/25 11:54
S65	82	S63 and map	US-PGPUB; USPAT	OR	ON	2005/07/25 12:04
S66	2856	(438/17).CCLS.	EPO; JPO	OR	OFF	2005/07/25 12:07
S67	28	S66 and map	EPO; JPO	OR	ON	2005/07/25 13:37

S73	1301	(700/121).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/26 11:12
S74	1301	(700/121).CCLS.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/26 11:12
S75	188	S73 and map	US-PGPUB; USPAT	OR	ON	2005/07/26 11:49
S77	275	(438/10).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/26 11:57
S79	9	pass/fail adj map	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 12:02
S81	1	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and classify adj electrical adj test	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 12:03
S82	7	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and classify adj2 test	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 12:04
S83	2	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and classify adj test	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 12:05
S84	0	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and analagous adj electrical adj test	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 12:05
S85	1	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and analogous adj electrical adj test	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 12:06
S86	0	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and (group grouping grouped categorize categorizing categorized) adj electrical adj test	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 12:06
S87	1	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and manufacturing adj records	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 12:07
S88	58	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and (manufactur\$3 with (history record))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 14:43
S89	2	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and fail adj density	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 14:44
S90	6	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and chi-square	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 14:49

S91	5	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and subarea	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/26 14:49
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